



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

John F. ARACKAPARAMBIL et al.

RECEIVE

AUG 0 1 2002

Serial No. 10/084,092

Group Art Unit: 2121

Technology Center 2100

Filed: February 28, 2002

Examiner:

For:

COMPUTER INTEGRATED MANUFACTURING TECHNIQUES

INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents Washington, D.C. 20231

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom. Copies of the references listed on pages 1 and 2 of Form PTO-1449 are submitted herewith.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

The references listed on Sheet Nos. 4 through 6 of Form PTO-1449 were cited by or submitted to the U.S. Patent and Trademark Office in parent application Serial No. 09/363,966, filed July 29, 1999, which is relied upon for an earlier filing date under 35 USC § 120. Copies of these references are not attached under 37 CFR 1.98(d).

This submission does not constitute a representation that a search has been made or that

no better art exists and does not constitute an admission or representation that any of the listed

documents is material or constitutes prior art. If it should be determined that any of the listed

documents does not constitute prior art under the United States law, Applicants reserve the right

to present to the Office the relevant facts and law regarding the appropriate status of such

document.

No certification or fee is believed to be required. However, the Commissioner is hereby

authorized to charge any additional fees should any be required for this submission, or credit any

overpayment to deposit account no. 08-0219.

Respectfully submitted,

HALE AND DORR LLP

Scott M. Alter

Registration No. 32,879

1455 Pennsylvania Avenue, NW

Washington, DC 20004

TEL 202.942.8428 SMA:lrr

FAX 202.942.8484

Date: $\frac{7/31/02}{}$

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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

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